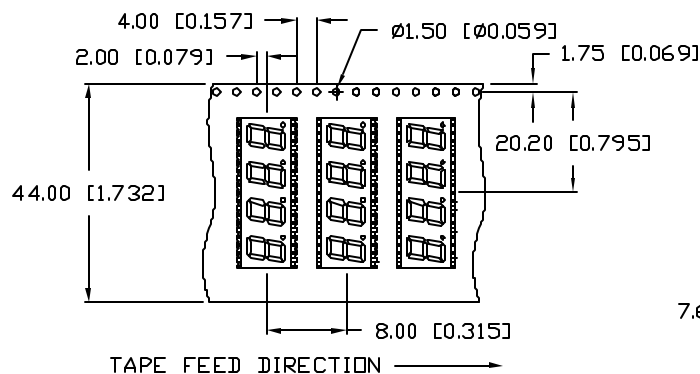
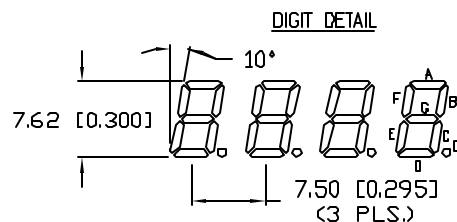
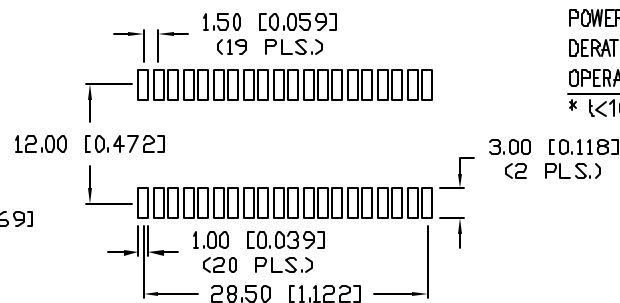


SOLDER PAD LAYOUT

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=10\text{mA}$

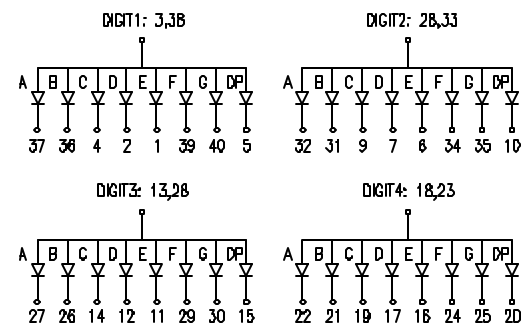
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		660 (RED)		nm	
FORWARD VOLTAGE		1.7	2.2	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_r=100\mu\text{A}$
AXIAL INTENSITY		6000		μcd	$I_f=10\text{mA}$
EMITTED COLOR:	RED				
FACE COLOR:	GRAY				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C

* $t < 10\mu\text{s}$

POLARITY DIAGRAM



*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: $X=\pm 1$ (± 0.039), $X.X=\pm 0.5$ (± 0.020), $X.XX=\pm 0.25$ (± 0.010), $X.XXX=\pm 0.127$ (± 0.005). LEAD SIZE= ± 0.05 (± 0.002), LEAD LENGTH= ± 0.75 (± 0.030). MIN.= ± 0.00 DECIMAL PRECISION MAX.= ± 0.00 DECIMAL PRECISION

REV.

PART NUMBER

LDQ-SMA3006RI-TR

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RELIABILITY NOTE

OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.



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TW WEB: www.lumex.com.tw

0.3" QUAD DIGIT SMT 7 SEGMENT DISPLAY, COMMON ANODE,
660nm RED CHIPS, GRAY FACE, MILKY WHITE DIFFUSED.

DRAWN BY:

GB

CHECKED BY:

APPROVED BY:

DATE: 10.9.03

PAGE: 1 OF 1

SCALE: N/A